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Declarations under Rule 4.17:

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[Continued on next page]

(54) Title: ELECTRONIC DEVICES FORMED OF TWO OR MORE SUBSTRATES BONDED TOGETHER, ELECTRONIC SYSTEMS COMPRISING ELECTRONIC DEVICES AND METHODS OF MAKING ELECTRONIC DEVICES

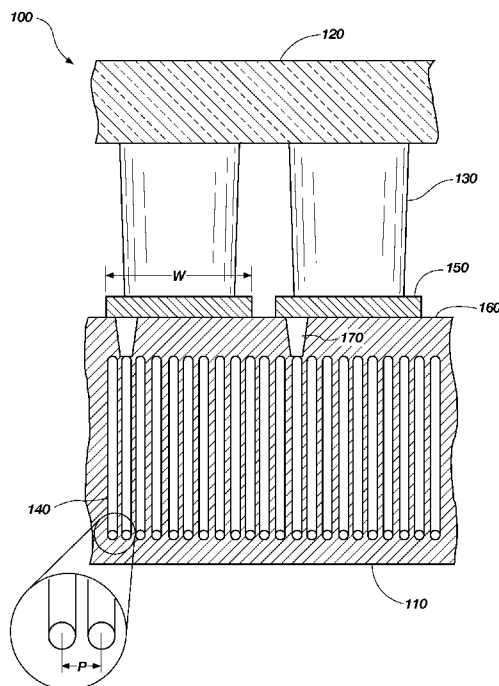


FIG. 1

(57) Abstract: Electronic devices comprise a first substrate and a second substrate. The first substrate comprises circuitry including a plurality of conductive traces at least substantially parallel to each other through at least a portion of the first substrate. A plurality of bond pads are positioned on a surface of the first substrate and comprise a width extending over at least two of the plurality of conductive traces. A plurality of vias extend from adjacent at least some of the conductive traces to the plurality of bond pads. The second substrate is bonded to the first substrate and comprises circuitry coupled to the plurality of bond pads on the first substrate with a plurality of conductive bumps. Memory devices and related methods of forming electronic devices and memory devices are also disclosed, as are electronic systems.

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